

Panel Discussion tomorrow: potting, encapsulating and underfills

We are delighted to have the opportunity to join this [Panel Discussion](#) tomorrow. Potting, encapsulating and underfills are all essential procedures in the assembly process. With miniaturization makes accurate, void-free processing important to maintain adequate support, protection and reliability. The panel will discuss the do's and don'ts of these processes, followed by a Q&A session. [Why don't you join us?](#)

POTTING, ENCAPSULATING AND UNDERFILLING



TREVOR
GALBRAITH
MODERATOR

PANEL DISCUSSION | TUESDAY, DECEMBER 1ST
7:30 AM PCT, 10:30 AM EST, 3:30 PM GMT AND 4:30 PM CET

GUESTS



RICHARD BOYLE
HENKEL



PETER SWANSON
INTERTRONICS



BOB WILLIS
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Supplied by:



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Last updated: November 2020

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